

REV.	ECN NO.	DATE
A	RELEASE	Jun 24, 2004
B	04'0645	Jun 25, 2004
C	05'0328	Mar 11, 2005
D	05'0420	Apr 09, 2005
E	05'1142	Nov 18, 2005
F	DRAW MODIFY	Sep 20, 2006
G	DRAW MODIFY	Oct. 25, 2006
H	DRAW MODIFY	Aug. 15, 2007

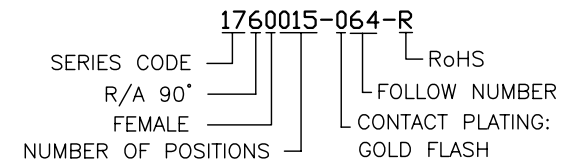
MATERIALS

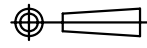
- HOUSING: HI.-TEMP.PLASTIC(UL 94V-0),BLUE.
- TERMINAL: COPPER ALLOY,t=0.30mm
GOLD PLATED ON CONTACT AREA,
TIN PLATED ON SOLDER TAIL,
UNDER NICKEL PLATED.
- PRONGS BOARDLOCK: COPPER ALLOY,t=0.50mm
TIN PLATED OVERALL
- SHELL: STEEL,NICKEL PLATED OVERALL,t=0.40mm
- RIVET: COPPER ALLOY.
NICKEL PLATED OVERALL.

SPECIFICATIONS

- CURRENT RATING: 1 A MAX.
- INSULATION RESISTANCE:
1000 MΩ MIN AT 500V DC.
- DIELECTRIC WITHSTANDING VOLTAGE:
500V AC R.M.S. FOR 1 MINUTE.
- CONTACT RESISTANCE: 30 mΩ MAX.
- OPERATING TEMPERATURE: -55°C TO +105°C.
- MAX. PROCESS TEMP. :
230°C FOR 30~60 SECONDS.
260°C FOR 10 SECONDS.

ORDER INFORMATION:



TOLERANCE		DRAWER	Astron
.0=±0.38 [.015]		B&N	
.00=±0.25 [.010]		CHECK	ASTRON TECHNOLOGY CORP.
.000=±0.15 [.006]		APP'D	NAME
.0000=±.		ERFB	HDD-SUB 15PIN SLIM TYPE II (RoHS)
ANG.=±3°		PRODUCT SPEC.	DRAW NO.
		UNITS : mm [inch]	R1760015-064
SCALE	SIZE	SHEET	REV.
NONE	A4	1 OF 1	H
			A0003

